	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	22	Yuan-ping.in.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 14:15
2	IS&R	L2	11	(("20010009301") or ("5942794") or ("5157457") or ("6483178") or ("6424024") or ("6400004")).PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 16:59
3	IS&R	L3	2	("5157475").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
4	IS&R	L4	1	("6548328").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 15:04
5	IS&R	L5	2	("5752182").PN.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/04/24 17:04

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	IS&R	L6	2	("6399415").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:05
7	BRS	L7	16	(seal$4 adj resin) near2 magnetic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 17:59
8	BRS	L8	170	multi adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 18:24
9	IS&R	L9	4	(("6399415") or ("5741729")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 18:24

-	7	Bayan-jaime.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 13:22
-	26	("5157475" | "5157480" | "5367196" | "5454905" | "5494207" | "5508556" | "5521429" | "5596231" | "5623123" | "5656550" | "5741729" | "5844315" | "5854511" | "5866948" | "5981314" | "5990545" | "6013946" | "6060774" | "6060778" | "6093960" | "6130473" | "6133070" | "6177288" | "6188130" | "6201292" | "6215179").PN.	USPAT	2003/04/23 13:09
-	170	ueno-yutaka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:00
-	247	257/711,684,730-731.ccls. and substrate and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:13
-	676	257/782-784,787-789,796.ccls. and substrate and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:21
-	34	257/782-784,787-789,796.ccls. and substrate with (metal adj layer) and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:26
-	5023	substrate with (metal adj layer) and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:44
-	1909	substrate with (metal adj layer) and (groove concave trench$4 recess$4) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 14:46
-	3832	substrate with (metal adj layer) and (groove concave trench$4 recess$4) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:03
-	724	substrate with (metal adj layer) with (groove concave trench$4 recess$4) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:05
-	4	257/711,684,730-731.ccls. and (multilayer adj substrate) and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:16
-	427	(multilayer adj substrate) and (groove concave trench$4 recess$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/23 15:18

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—	36	(("5633204") or ("5508561") or ("6259161") or ("6288851") or ("6278190") or ("6344682") or ("6184061") or ("5986336") or ("5959353") or ("6270202") or ("5900582") or ("5969463") or ("5910699") or ("5925973") or ("5724726") or ("5763829") or ("5281818") or ("5291484") or ("4831636")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:35
—	429	(reaction adj layer) and laminat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
—	66	(reaction adj layer) and laminat$4 and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:03
—	17	438/615.ccls. and laminat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:10
—	580	438/613-617.ccls. and press$4 and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:19
—	488	438/613-617.ccls. and press$4 and heat$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:23
—	0	((masamoto adj tago) (Yoshihiro adj tomita)) and press$4 and heat$4 and (bump ball) and (chip die IC substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:02
—	5	tago-masamoto.in. and heat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:11
—	2	tago-masamoto.in. and Tomita-yoshihiro.in. and heat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:12
—	27	Tomita-yoshihiro.in. and heat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:18
—	24	(("5229647") or ("5418687") or ("5440241") or ("5506383") or ("5682062") or ("5685885") or ("5742100") or ("5767575") or ("5892288") or ("5973396") or ("5990546") or ("6004867")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/10 15:56
—	3	("3171643").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 11:47
—	2	("2002170919").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/14 11:47

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-	1	irradiating adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	1	irradiat$4 adj radical adj fluorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:26
-	0	activating and sputerring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:27
-	9	activat$4 and sputterring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	activat$4 with sputterring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:29
-	0	sputterr$4 and (reduction adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:30
-	0	sputterr$4 and (reduct$4 adj gas)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:40
-	2	("2002110726").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:56
-	133	multi-layer and solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	1603	solder and intermetallic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:04
-	581	solder and intermetallic and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:05
-	310	solder and intermetallic and (bump ball) and press$4 and (heat$4 reflow$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:18
-	6	(("6344696") or ("5633204") or ("5508561")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 15:27

L Number	Hits	Search Text	DB	Time stamp
-	4	257/737-738.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:37
-	1	257/779.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:38
-	0	257/685-686.ccls. and (bump ball) and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:39
-	577	257/685-686.ccls. and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:43
-	0	257/685-686.ccls. and (supersonic adj wave)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:44
-	128	257/685-686.ccls. and laminat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 13:54
-	157	438/613-617.ccls. and laminat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 16:18
-	90	438/612.ccls. and laminat$4 and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:14
-	419	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:16
-	136	438/612.ccls. and ((irrfaiating adj radical adj fluorine) (reduction adj gas) sputter$4) and press$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:22
-	1	(atomic adj beam) with (inactive adj gas adj excited) near3 plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:23
-	1	(atomic adj beam) with (inactive adj gas adj excited) with plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:24
-	1	(atomic adj beam) and (inactive adj gas adj excited) and plasma	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 14:25